

# Hex Inverting Schmitt Trigger

# MM74HCT14

### **Description**

The MM74HCT14 utilizes advanced silicon-gate CMOS technology to achieve the low power dissipation and high noise immunity of standard CMOS, as well as the capability to drive 10 LS-TTL loads.

The 74HCT logic family is functionally and pinout–compatible with the standard 74LS logic family. Inputs are protected from damage due to static discharge by internal diode clamps to  $V_{\rm CC}$  and ground.

#### **Features**

- Typical Propagation Delay: 10 ns
- Wide Power Supply Range: 4.5 V 5.5 V
- Low Quiescent Current: 10 µA Maximum
- Low Input Current: 1 μA Maximum
- Fanout of 10 LS-TTL Loads
- Typical Hysteresis Voltage: 0.6 V at  $V_{CC} = 4.5 \text{ V}$
- TTL, LS Pin-out and Input Threshold Compatible
- This Device is Pb-Free, Halide Free and is RoHS Compliant

#### **Connection Diagram**

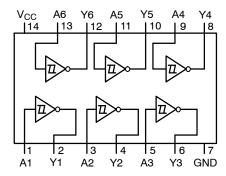


Figure 1. Pin Assignments

# **Schematic Diagram**

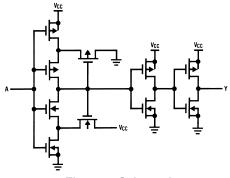


Figure 2. Schematic

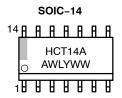
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## **MARKING DIAGRAMS**





14A ALYW• O •

HCT14A = Specific Device Code A = Assembly Location WL, L = Wafer Lot Number

Y = Year WW, YW = Work Week

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 4 of this data sheet.

#### MM74HCT14

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Rating	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	-0.5	+7.0	V
V <sub>IN</sub>	DC Input Voltage	-0.5	V <sub>CC</sub> + 0.5	V
V <sub>OUT</sub>	DC Output Voltage	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub> , I <sub>OK</sub>	Clamp Diode Current		±20	mA
I <sub>OUT</sub>	DC Output Current, Per Pin		±25	mA
I <sub>CC</sub>	DC V <sub>CC</sub> or GND Current, Per Pin		±50	mA
T <sub>STG</sub>	Storage Temperature Range	-65	+150	°C
$T_L$	Lead Temperature (Soldering 10 second)		+260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	4.5	5.5	V
V <sub>IN</sub> , V <sub>OUT</sub>	DC Input or Output Voltage	0	$V_{CC}$	V
T <sub>A</sub>	Operating Temperature Range	-40	+85	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

# DC ELECTRICAL CHARACTERISTICS

				T <sub>A</sub> =	+25°C	T <sub>A</sub> = -40 to +85°C	
Symbol	Parameter	Conditions	V <sub>CC</sub>	Тур	Guaranteed Limits		Unit
$V_{T+}$	Positive-Going	Minimum	4.5	1.5	1.2	1.2	V
	Threshold Voltage		5.5	1.7	1.4	1.4	
		Maximum	4.5	1.5	1.9	1.9	
			5.5	1.7	2.1	2.1	7
$V_{T-}$	Negative-Going	Minimum	4.5	0.9	0.5	0.5	V
	Threshold Voltage		5.5	1.0	0.6	0.6	
		Maximum	4.5	0.9	1.2	1.2	]
			5.5	1.0	1.4	1.4	]
$V_{H}$	Hysteresis Voltage	Minimum	4.5	0.6	0.4	0.4	V
			5.5	0.7	0.4	0.4	
		Maximum	4.5	0.6	1.4	1.4	
			5.5	0.7	1.5	1.5	
V <sub>OH</sub>	Minimum HIGH Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT}  = 20 \ \mu A$	4.5	V <sub>CC</sub>	V <sub>CC</sub> - 0.1	V <sub>CC</sub> – 0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT}  = 4.0 \text{ mA}$	4.5	4.20	3.98	3.84	
		$V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT}  = 4.8 \text{ mA}$	5.5	5.20	4.98	4.98	
V <sub>OL</sub>	Maximum LOW Level Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT}  = 20 \ \mu\text{A}$	4.5	0	0.1	0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT}  = 4.0 \text{ mA}$	4.5	0.2	0.26	0.33	
		$V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT}  = 4.8 \text{ mA}$	5.5	0.2	0.26	0.33	
I <sub>IN</sub>	Maximum Input Current	V <sub>IN</sub> = V <sub>CC</sub> or GND, V <sub>IH</sub> or V <sub>IL</sub>	5.5		±0.1	±1.0	μΑ

#### MM74HCT14

#### DC ELECTRICAL CHARACTERISTICS (continued)

				T <sub>A</sub> = +	-25°C	T <sub>A</sub> = -40 to +85°C	
Symbol	Parameter	Conditions	V <sub>CC</sub>	Тур	Guai	ranteed Limits	Unit
I <sub>CC</sub>	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0 \mu A$	5.5		1.0	10.0	μΑ
		V <sub>IN</sub> = 2.4 V or 0.5 V			2.4	2.4	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **AC ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C}, C_L = 15 \text{ pF}, t_r = t_f = 6 \text{ ns})$ 

Symbol	Parameter	Тур	Guaranteed Limit	Unit
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay	10	18	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **AC ELECTRICAL CHARACTERISTICS**

(Unless otherwise specified,  $V_{CC}$  = 5.0 V ±10%,  $C_L$  = 50 pF,  $t_r$  =  $t_f$  = 6 ns)

			T <sub>A</sub> = +25°C		T <sub>A</sub> = -40 to +85°C	
Symbol	Parameter	Conditions	Тур	Guai	ranteed Limits	Unit
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay			20	25	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Rise and Fall Time		9	15	19	ns
C <sub>PD</sub>	Power Dissipation Capacitance (Note 1)	Per Gate		25		pF
C <sub>IN</sub>	Maximum Input Capacitance		5	10	10	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1.  $C_{PD}$  determines the no-load dynamic power consumption,  $P_D = C_{PD} \, V_{CC}^2 f + I_{CC} \, V_{CC}$ , and the no load dynamic current consumption,

#### **Typical Applications**

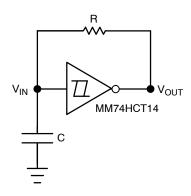


Figure 3. Low Power Oscillator

Figure 4. Oscillator Input and Output Waveforms

The following equations assume  $t_1 + t_2 >> t_{pd0} + t_{pd1}$ :

$$t_2 \approx RCIn \frac{V_{CC} - V_{T-}}{V_{CC} - V_{T+}} \tag{eq. 1}$$

$$f \approx \frac{1}{\text{RCIn} \frac{V_{T+}(V_{CC} - V_{T-})}{V_{T-}(V_{CC} - V_{T+})}}$$
 (eq. 2)

 $I_S = C_{PD} V_{CC} f + I_{CC}$ 

# MM74HCT14

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MM74HCT14M	SOIC-14 NB, Case 751A-03 (Pb-Free and Halide Free)	55 Units / Tube
MM74HCT14MX	SOIC14, Case 751EF (Pb-Free and Halide Free)	2500 Units / Tape & Reel
MM74HCT14MTCX	TSSOP-14 WB, Case 948G (Pb-Free and Halide Free)	2500 Units / Tape & Reel

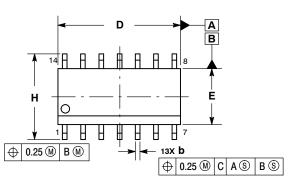
For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, <u>BRD8011/D</u>.

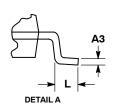


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SOIC-14 NB CASE 751A-03 ISSUE L

**DATE 03 FEB 2016** 





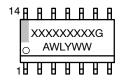




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
  - ASME Y14.5M, 1994.
    CONTROLLING DIMENSION: MILLIMETERS.
  - DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT
  - MAXIMUM MATERIAL CONDITION.
    DIMENSIONS D AND E DO NOT INCLUDE
    MOLD PROTRUSIONS.
- MAXIMUM MOLD PROTRUSION 0.15 PER SIDE

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.35	1.75	0.054	0.068	
A1	0.10	0.25	0.004	0.010	
АЗ	0.19	0.25	0.008	0.010	
b	0.35	0.49	0.014	0.019	
D	8.55	8.75	0.337	0.344	
Е	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.019	
L	0.40	1.25	0.016	0.049	
M	0 °	7°	0 °	7 °	

#### **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code Α = Assembly Location

WL = Wafer Lot Υ = Year WW = Work Week = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

# SOI DERING FOOTBRINT\*

	SOLDERING	FOOTPRINT*	
1	6.5	50	14X - 1.18
			1.27
	——————————————————————————————————————		PITCH
14X A			
14X 0.58			

**DIMENSIONS: MILLIMETERS** 

# **STYLES ON PAGE 2**

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# SOIC-14 CASE 751A-03 ISSUE L

# DATE 03 FEB 2016

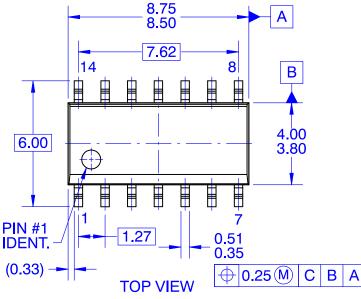
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STYLE 5: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. NO CONNECTION 7. COMMON ANODE 8. COMMON CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 6: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. ANODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE	STYLE 7: PIN 1. ANODE/CATHODE 2. COMMON ANODE 3. COMMON CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. ANODE/CATHODE 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. COMMON CATHODE 12. COMMON ANODE 13. ANODE/CATHODE 14. ANODE/CATHODE	STYLE 8: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. ANODE/CATHODE 7. COMMON ANODE 8. COMMON ANODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. NO CONNECTION 12. ANODE/CATHODE 13. ANODE/CATHODE 14. COMMON CATHODE

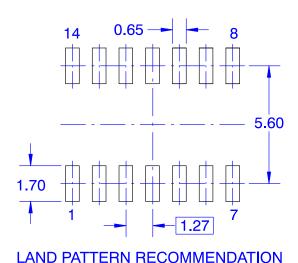
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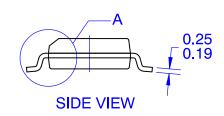
SOIC14 CASE 751EF ISSUE O

**DATE 30 SEP 2016** 



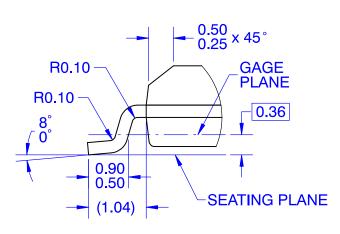


1.75 MAX 0.10 1.50 0.25 0.10 1.25 **FRONT VIEW** 



# **NOTES:**

- A. CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C
  B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
- LAND PATTERN STANDARD: SOIC127P600X145-14M
- E. CONFORMS TO ASME Y14.5M, 2009

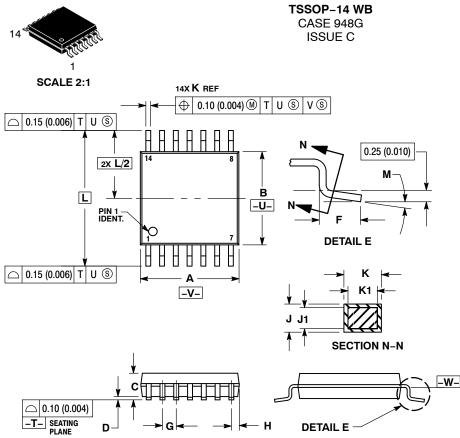


DETAIL A SCALE 16:1

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**SOLDERING FOOTPRINT** 

7.06

14X

1.26

**DATE 17 FEB 2016** 

- NOTES.

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD
- FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  DIMENSION B DOES NOT INCLUDE
- INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

  6. TERMINAL NUMBERS ARE SHOWN FOR DEFERENCE ONLY
- REFERENCE ONLY.
  DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-.

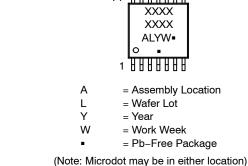
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
М	0°	8 °	0 °	8 °

# **GENERIC MARKING DIAGRAM\***

XXXX XXXX

ALYW= O 1 1000000

= Assembly Location = Wafer Lot



= Work Week = Pb-Free Package

- Year

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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DIMENSIONS: MILLIMETERS

0.65

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14X

0.36

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Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

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